

## 1. Soldering

### (1) Re-flow soldering

Please mount component on a circuit board by re-flow soldering. Flow soldering is not acceptable.

#### Recommendable Flux and Solder

Flux	Please use rosin based flux, but do not use water soluble flux.
Solder	Please use solder (Sn-3.0Ag-0.5Cu) under the following condition. Standard thickness of soldering paste: 0.10 to 0.15mm

#### Recommendable Soldering Profile

Pre-heating	150 to 180°C	60 to 120s
Heating	220°C min.	30 to 60s
Peak Temperature	upper limit: 260°C	1s max.
	lower limit: 245°C	5s max.

Temperature shall be measured on the surface of component.

### (2) Soldering with iron

Be compelled to mount component by using soldering iron, please do not directly touch the component with soldering iron. The terminals of component or electrical characteristics may be damaged if excess thermal stress is applied.

#### Recommendable Soldering with Iron

Heating of the soldering iron	350°C max.
Watt	30W max.
Shape of the soldering iron	ø3mm max.
Soldering Time	5s max. at one terminal
Solder	Sn-3.0Ag-0.5Cu

### (3) Solder Volume

Please make the solder volume less than the height of the substrate. When exceeding the substrate, the damage of adhesive for sealing between the metal cap and the substrate may occur.

### (4) etc.

Do not reuse removed component from a circuit board after soldering.

### (5) Condition for Placement machines

The component is recommended with placement machines with employ optical placement capabilities. The component might be resulted in damage by excessive mechanical force. Please make sure that you have evaluated by using placement machines before going into mass production. Do not use placement machines which utilize mechanical positioning. Please contact Murata for details beforehand.

## 2. Washing / Coating

Conformal coating or washing to the component is not acceptable, because it is not hermetically sealed.

Please contact us in case you need washable component.

